

Critical Conduction Mode PFC IC FA5590N / FA5591N

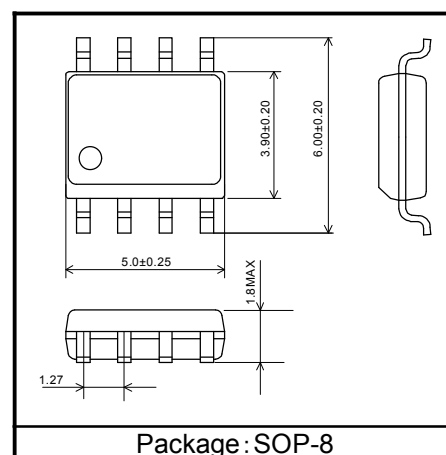
Datasheet

1. Overview

FA5590/FA5591 is power-factor correction converter IC operating in critical conduction mode. It realizes low power consumption by using high voltage CMOS process. It is equipped with many fault protection functions such as FB short-circuit detection circuit which stops the operation when abnormal output voltage is detected.

2. Features

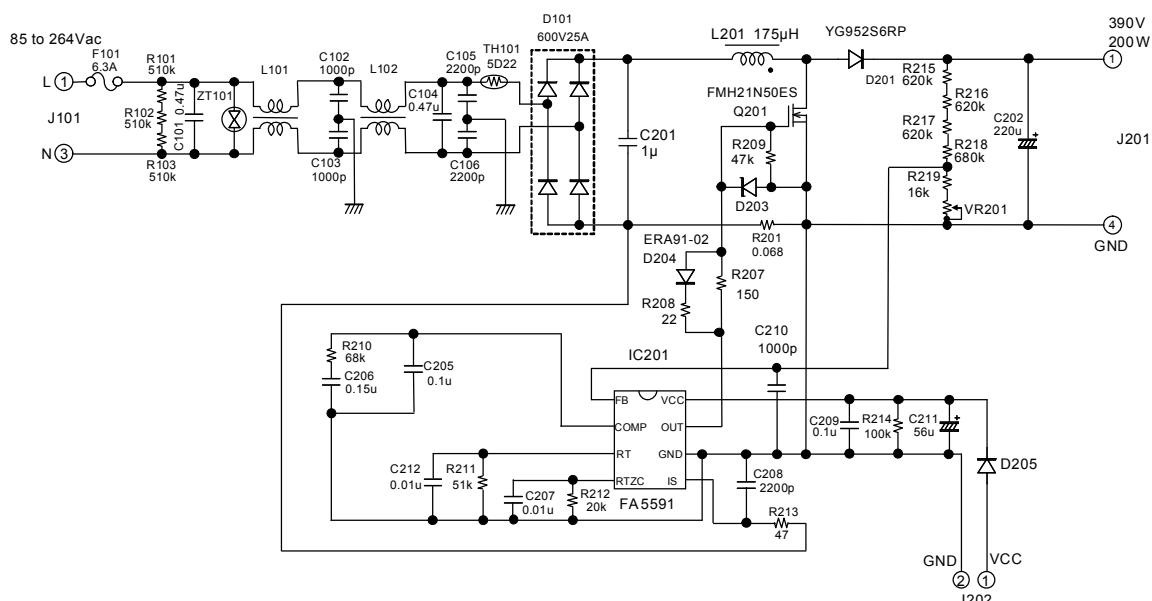
- Very Low Standby Power by disusing Input Voltage Detection Resistors
- High-precision over current protection : $0.6V \pm 5\%$
- Improved power efficiency at light load due to Maximum Frequency Limitation
- No Audible Noise at Startup
 - Soft-Startup and Soft-OVP functions
- Low current consumption by CMOS process
 - Start-up : $80\mu A(\text{max.})$, Operating : $2\text{mA}(\text{typ.})$
- Enabled to drive power MOSFET directly
 - Output peak current, source : 500mA , sink : 1000mA
- Open/short protection at feedback (FB) pin
- Under-voltage Lockout
 - FA5590: $9.6V \text{ ON} / 9V \text{ OFF}$ FA5591: $13V \text{ ON} / 9V \text{ OFF}$
- Overvoltage protection
- Restart timer
- Standby function
- 8-pin package (SOP)



3. Function list by types

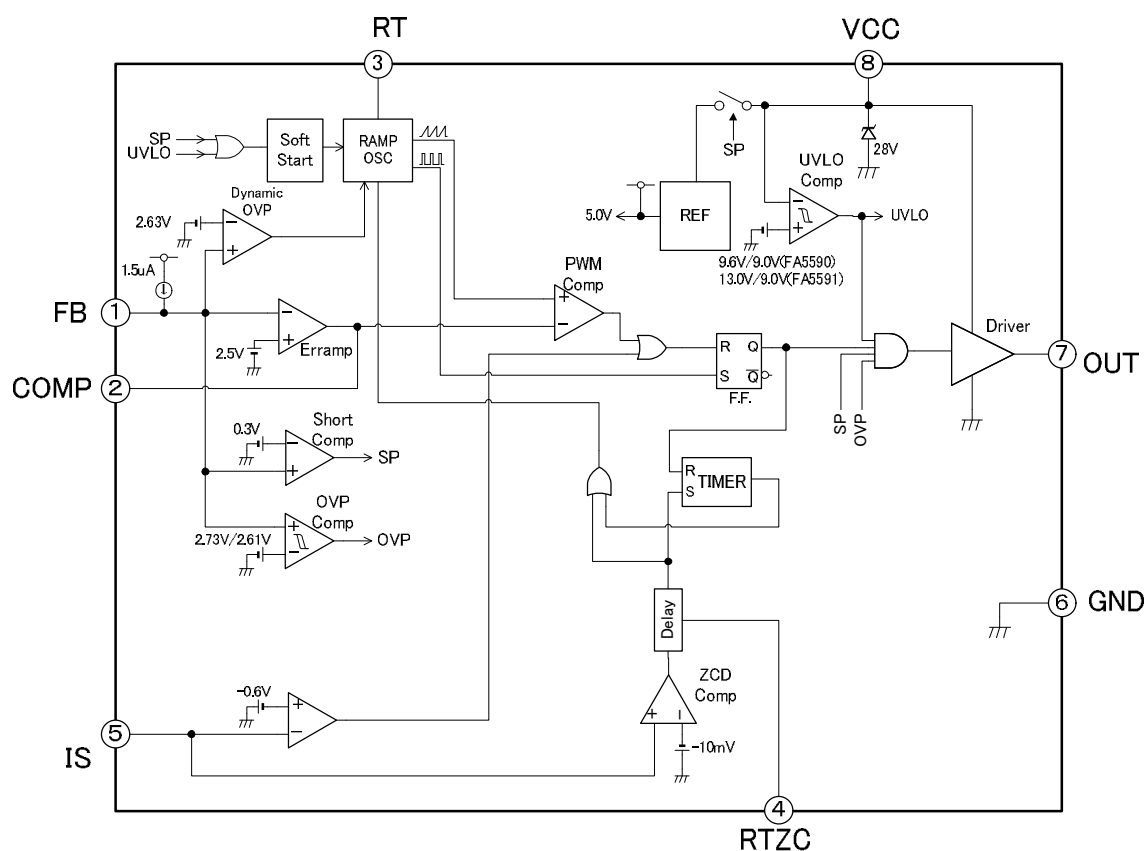
Type	Startup Threshold
FA5590N	9.6V(typ.)
FA5591N	13V(typ.)

4. Application circuit example



5. Block diagram

FA5590N / FA5591N

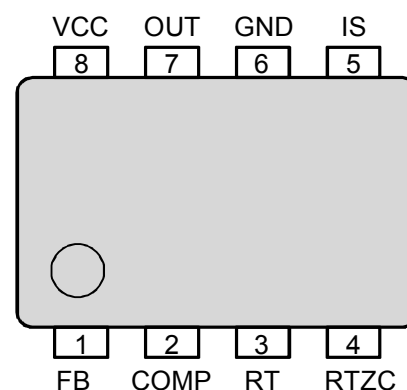


6. Functional description of pins

Pin No.	Pin name	Pin Function
1	FB	Feedback Voltage Input *1
2	COMP	Compensation *1
3	RT	Set Maximum on time *1
4	RTZC	Set Delay time *1
5	IS	Current Sense Input *1
6	GND	Ground
7	OUT	Output
8	VCC	Power Supply *1

Notes)

*1 connect the capacitor.



7. Rating & characteristics

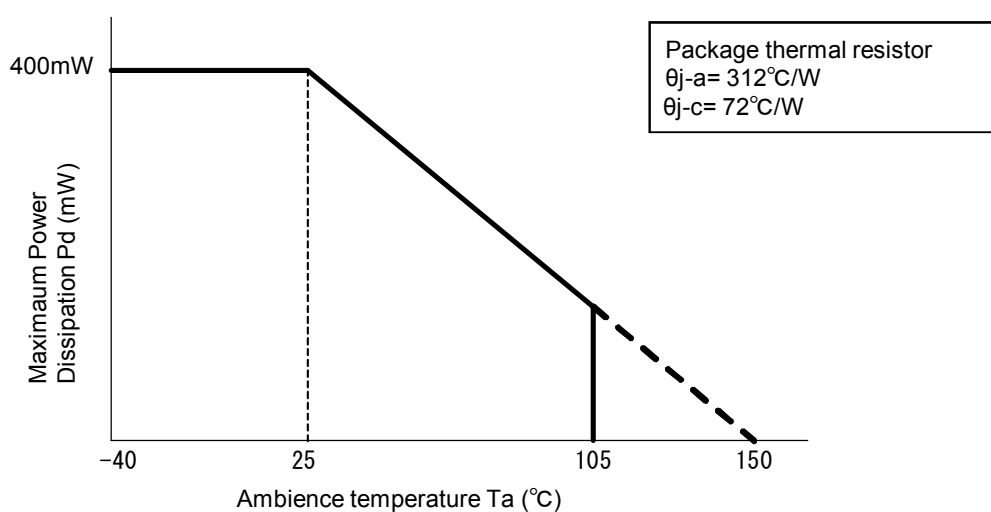
Stress exceeding absolute maximum ratings may malfunction or damage the device.

“-” shows source and “+” shows sink in current descriptions.

(1) Absolute maximum ratings

Item	Symbol	Value	Unit
Total Power Supply and Zener Current	I _{vcc+Iz}	15	mA
Supply Voltage	V _{cc}	28	V
Output Peak Current Source or Sink	I _o	-500 to 1000	mA
Control pin input voltage(FB,COMP,RT,RTZC)	V _{infb} , V _{incomp} , V _{inrt} , V _{inrtzc}	-0.3 to 5	V
Control pin input voltage(IS)	V _{inis}	-5 to 0.3	V
Control pin input current(FB,COMP,RT,RTZC)	I _{infb} , I _{incomp} , I _{inrt} , I _{inrtzc}	-100 to 100	uA
Power dissipation(Ta=25°C)	P _d	400	mW
Operating Junction Temperature	T _j	-40 to 150	°C
Storage Temperature	T _{stg}	-40 to 150	°C

※Maximum dissipation curve



(2) Recommended operating conditions

Item	Symbol	Min.	Typ.	Max.	Unit
Supply Voltage	V _{cc}	10	12	26	V
VCC pin electrolytic capacitor	C _{vcce}	10	-	-	uF
VCC pin ceramic capacitor	C _{vcce}	0.1	-	-	uF
RT pin resistance	R _{rt}	20	82	150	kΩ
RTZC pin resistance	R _{rtzc}	0	47	150	kΩ
FB pin resistance	R _{fb}	-	-	8	MΩ
IS pin filter resistance	R _{isf}	-	-	100	Ω
Operating Ambient Temperature	T _a	-40	-	105	°C

(3) DC electrical characteristics

The characteristics in this section are those in conditions as follows unless otherwise specified. The voltages described in the conditions are DC input, not AC input.

$T_j=25^{\circ}\text{C}$, $V_{CC}=12\text{V}$, $V(\text{FB})=1.0\text{V}$, $V(\text{COMP})=5\text{V}$, $V(\text{IS})=100\text{mV}$, OUT open, $R_{\text{rt}}=82\text{k}\Omega$, $R_{\text{rtzc}}=47\text{k}\Omega$

Notes)

(1) The item which indicated “*1” are not 100% tested and guaranteed by design.

(2) “-” means that it is not guaranteed.

(3) “-” shows source current and “+” shows sink current in output characteristics.

ERROR AMPLIFIER (FB Pin, COMP Pin)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Voltage Feedback Input Threshold	Vfb		2.465	2.500	2.535	V
Line Regulation	Regline	$V_{CC}=10\text{V}$ to 26V	-20	-10	-	mV
Temperature stability	VdT	$T_j=-30^{\circ}\text{C}$ to 85°C	-	± 0.5	-	mV/ $^{\circ}\text{C}$
Transconductance	Gm	$V_{\text{FB}}(\text{DC})=2.25\text{V}$, 2.75V $V_{\text{COMP}}(\text{DC})=2.5\text{V}$ $G_m=I_{\text{comp_}2.75}-I_{\text{comp_}2.25}/(2.75-2.25)$	50	75	100	μmho
Output Current	Io	Source: $V(\text{FB})=1.0\text{V}$ $V(\text{COMP})=2.5\text{V}$	-60	-50	-20	μA
		Sink: $V(\text{FB})=4.0\text{V}$ $V(\text{COMP})=2.5\text{V}$	30	50	70	

RAMP OSCILLATOR (RT Pin)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Maximum on range	Tonmax	$V(\text{FB})=V_{\text{fb}}$	20	26	32	μs
Maximum on range (Soft start)	Tonmax_soft-start	$V(\text{COMP})=5.0\text{V}$ $V(\text{FB})=1.0\text{V}$	14	20	26	μs
Maximum on time hysteresis width	Tonmax_hys	$T_{\text{onmax}} - T_{\text{onmax_ss}}$	4	6	8	μs
Maximum oscillating frequency	Fmax	$V(\text{COMP})=0.8\text{V}$ $R_{\text{rtzc}}=20\text{k}\Omega$	300	360	420	kHz
RT output voltage	Vrt		0.90	1.15	1.40	V

PWM COMPARATER (COMP Pin)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Input threshold voltage	Vthcomp	$V(\text{COMP})$ decrease	0.6	0.7	0.8	V

SOFT START (FB Pin)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
End voltage of soft-start	Vthsoft	$V(\text{FB})$ increase $T_{\text{on}}=T_{\text{onmax}} * 0.9$	0.915 * Vfb	0.950 * Vfb	0.985 * Vfb	V

OVERVOLTAGE COMPARATER (FB Pin)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Static OVP threshold voltage	Vsovph	$V(\text{FB})$ increase	1.070 $\times V_{\text{fb}}$	1.090 $\times V_{\text{fb}}$	1.105 $\times V_{\text{fb}}$	V
	Vsovpl	$V(\text{FB})$ decrease	1.025 $\times V_{\text{fb}}$	1.045 $\times V_{\text{fb}}$	1.065 $\times V_{\text{fb}}$	V
	Vsovphys	$V_{\text{sovph}} - V_{\text{sovpl}}$	0.020 $\times V_{\text{fb}}$	0.040 $\times V_{\text{fb}}$	0.060 $\times V_{\text{fb}}$	V
Dynamic OVP threshold voltage	Vdovp	$V(\text{FB})$ increase $T_{\text{on}}=T_{\text{onmax}} * 0.7$	1.025 $\times V_{\text{fb}}$	1.050 $\times V_{\text{fb}}$	1.075 $\times V_{\text{fb}}$	V

FB SHORT COMPARATOR (FB Pin)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Input threshold voltage	Vthfb	$V(\text{FB})$ decrease	0.1	0.3	0.5	V
Pull-up current	Ipullup	$V(\text{FB})=2.5\text{V}$	1.2	1.8	2.4	μA

CURRENT SENSE COMPARATOR (IS Pin)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
IS threshold voltage	Vthis	V(IS) pulse : High = 100mV, Low decrease, dV/dT = $\pm 40\text{V}/\mu\text{s}$	-0.62	-0.60	-0.58	V
IS threshold voltage temperature characteristics *1	Vthisdt	Tj = -30°C to +85°C	-1.5	-	1.5	%
Output delay	Tphl	V(IS) pulse : High = 100mV, Low = -100mV, dV/dT = -40V/ μs , OUT open	-	200	500	ns
Zero current detection voltage	Vzcd	V(ZCD) increase	-15.0	-10.0	-5.0	mV
Zero current detection delay	Tzcd	V(IS) pulse : High = 100mV, Low = -100mV, dV/dT = +40V/ μs , OUT open, Rtzc = 47k Ω	1.0	1.5	2.0	μs
RTZC output voltage	Vrtzc		0.90	1.15	1.40	V

Driver output (OUT Pin)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Output voltage (L)	Vol	Isink=200mA	-	1.2	3.3	V
Output voltage (H) *1	Voh	Isouce=200mA	7.8	8.4	-	V
Output rise time	Tr	CL=1.0nF	-	50	120	ns
Output fall time	Tf	CL=1.0nF	-	25	100	ns

Restart timer

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Restart timer delay *1	Tdly	V(FB) increase	-	20	-	μs

Under voltage lock out (VCC Pin)

Item	Symbol	Condition		Min.	Typ.	Max.	Unit
Startup threshold voltage	Von	VCC increase	FA5590N	8.6	9.6	10.6	V
			FA5591N	11.5	13	14	V
Shutdown threshold voltage	Voff			8	9	10	V
UVLO hysteresis width	Vhysvcc	Von – Voff	FA5590N	0.3	0.6	0.9	V
			FA5591N	3.0	4.0	5.0	V

Power supply current (VCC Pin)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Startup power supply current	Istart	VCC = Von-0.1V	-	-	80	μA
Operating power supply current	Icc	CL=OPEN	-	1.5	3.0	mA
Dynamic operating power supply current	Iop	CL=1.0nF	-	2.0	4.0	mA
Stand-by current	Istb	V(FB)=0V, V(COMP)=0V	-	30	60	μA

8. Characteristic curve

The characteristics in this section are those in conditions as follows unless otherwise specified.

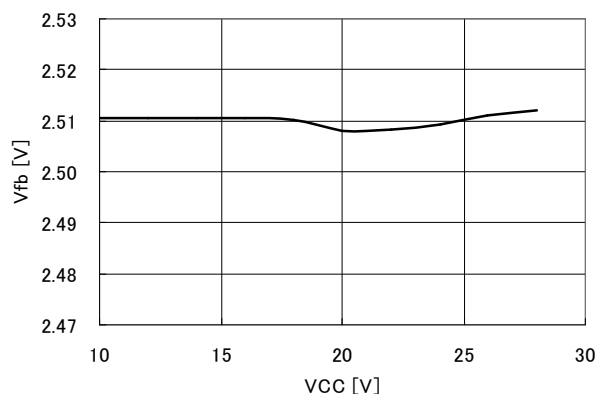
$T_j = 25^\circ\text{C}$, $V_{CC} = 12\text{V}$, $V(\text{FB}) = 1.0\text{V}$, $V(\text{COMP}) = 5\text{V}$, $V(\text{IS}) = 100\text{mV}$, OUT open, $R_{\text{rt}} = 82\text{K}\Omega$, $R_{\text{tzc}} = 47\text{K}\Omega$

Notes)

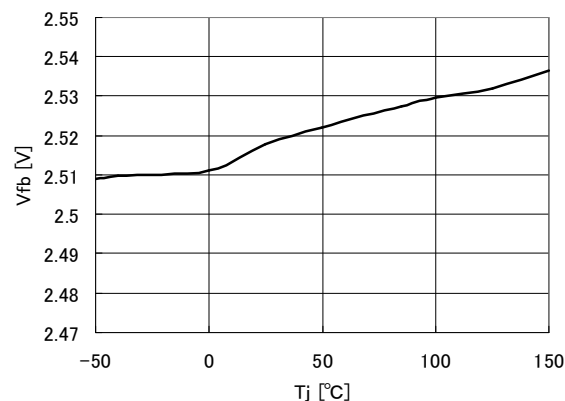
(1) "-" shows source current and "+" shows sink current.

(2) The data listed here show the typical characteristics of an IC and it does not guarantee the characteristic.

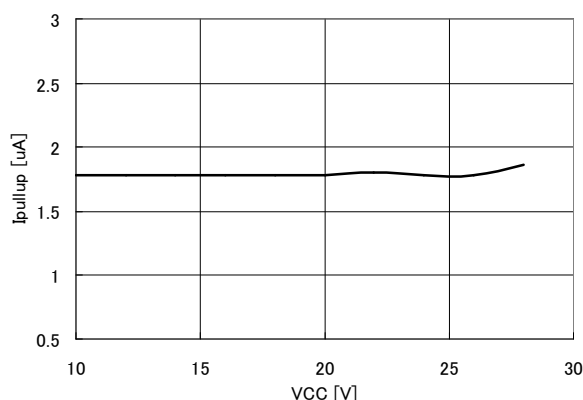
Error amplifier voltage feedback input threshold(V_{fb}) vs. supply voltage(V_{CC})



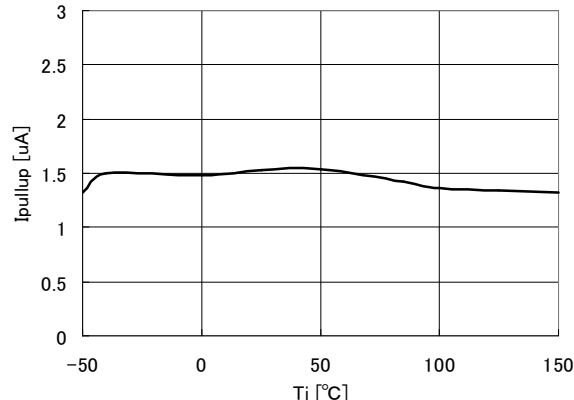
Error amplifier voltage feedback input threshold(V_{fb}) vs. junction temperature(T_j)



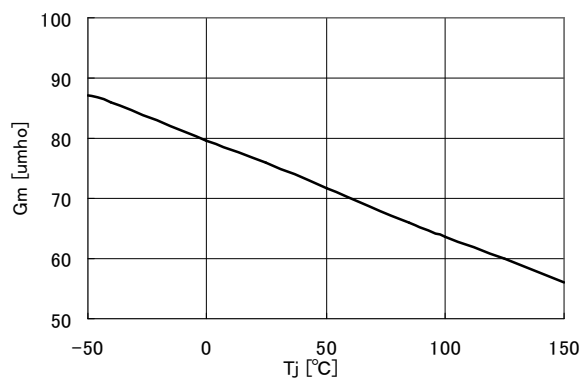
FB pull-up current(I_{pullup}) vs. supply voltage(V_{CC})



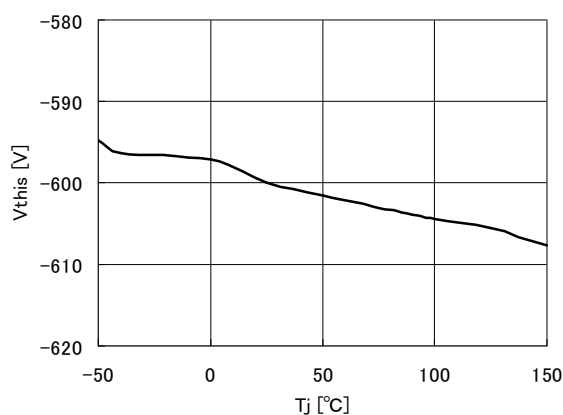
FB pull-up current(I_{pullup}) vs. junction temperature(T_j)



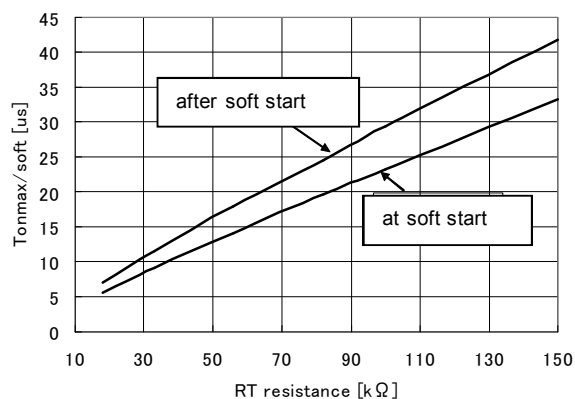
Error amplifier transconductance(G_m) vs. junction temperature(T_j)



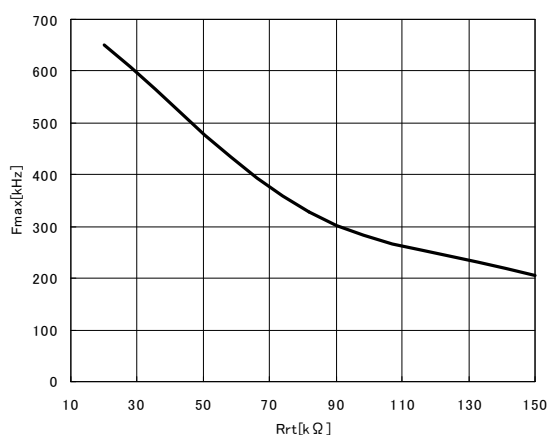
Current sense comparator maximum threshold(V_{this}) vs. supply voltage(V_{cc})



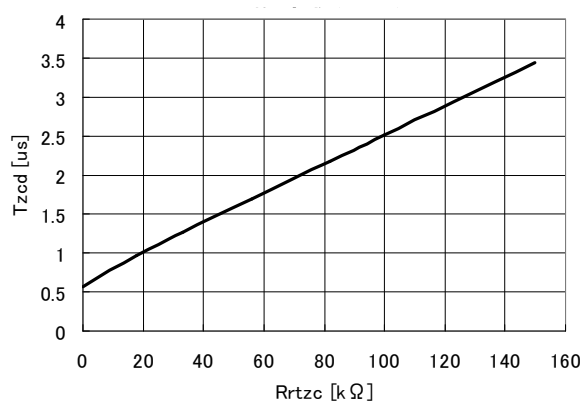
Maximum on-range(T_{onmax}) vs. RT resistance(R_t)



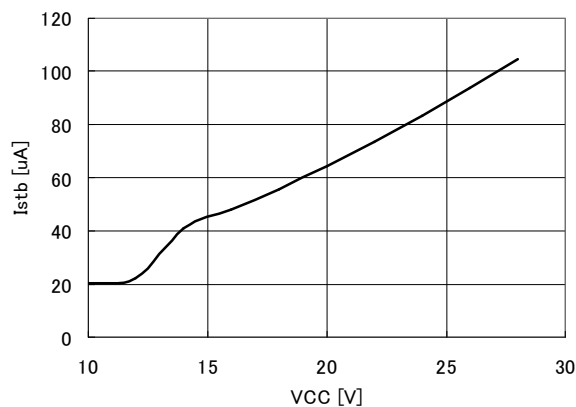
Maximum oscillating frequency(F_{max}) vs. RT resistance(R_t)



Zero current detection delay(T_{zcd}) vs. RTZC resistance(R_{tzc})



Standby current(I_{stb}) vs. supply voltage(V_{cc})



9. Outline of circuit operation

This IC is a power-factor correction converter utilizing a boosting chopper, operating in critical mode. Hereinafter is outline of the operation consisting of switching operation and power-factor correction operation using the circuit diagram shown in Fig. 1.

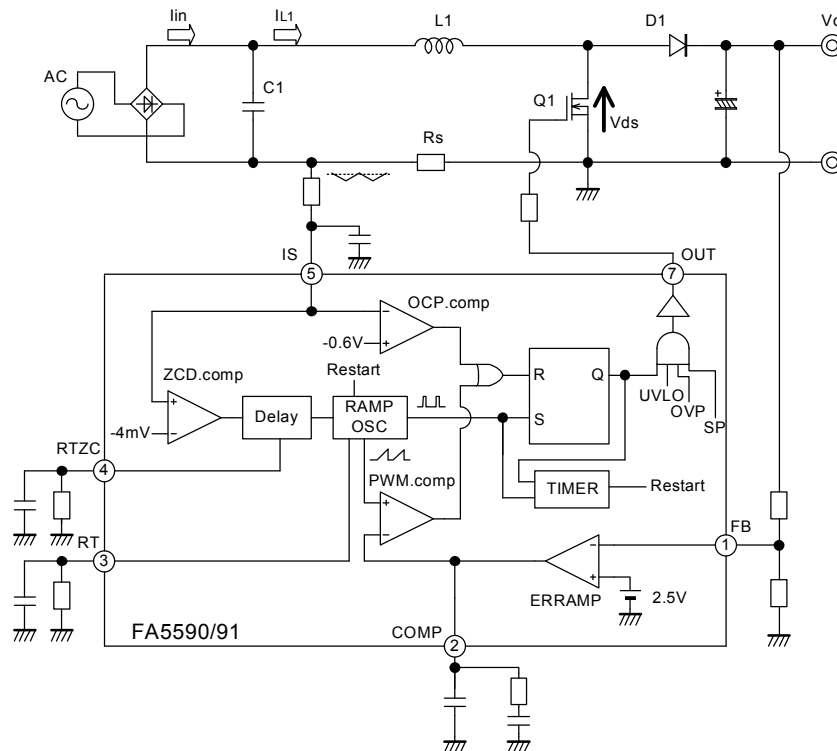


Fig.1 Block diagram of operating circuit

(1) Switching operation

This IC performs the switching operation in the critical mode applying self-oscillation without using an oscillator. Fig.2 shows the outline of waveforms of the switching operation in steady state. The operation is as follows.

- [t1]** Q1 turns on, the current through inductor ($L1$) rises from zero. At the timing of Q1 on, V_{ramp} ; output of ramp generator states to rise.
- [t2]** V_{ramp} and V_{comp} ; output of the error amplifier are compared by the PWM comparator, and when $V_{ramp} > V_{comp}$, Q1 turns off and the output of the ramp generator drops. When Q1 turns off, the voltage across $L1$ inverts and the current through $L1$ decreases while the current is supplied to the output side through $D1$.
- [t3]** The current through $L1$ is detected by IS pin, and when the current becomes zero, the output of the current detection comparator becomes High to turn on Q1 after delay given by the delay circuit, thus moving to the next switching cycle ($t1$).

By repeating the operations of $t1 \sim t3$, the switching in critical mode is continued.

With the power-factor correction circuit in the critical mode, the switching frequency is always changing due to instantaneous values of the AC input voltage. The switching frequency also changes when the input voltage or load changes.

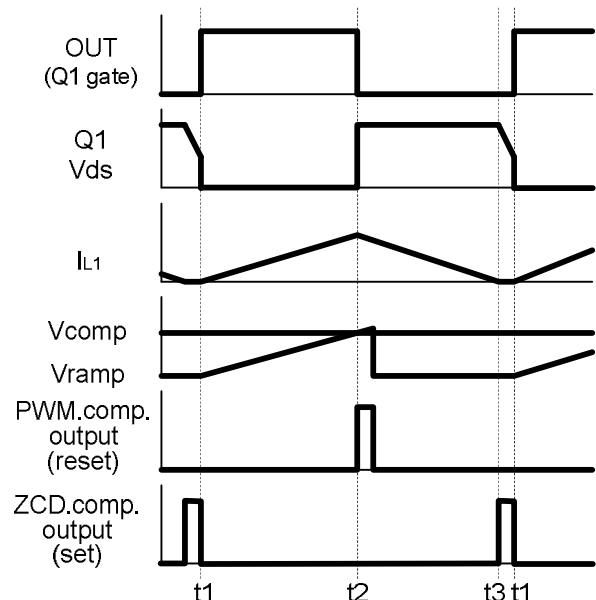


Fig. 2 Switching Operation, Waveforms

(2) Power-factor correction operation

As explained in the switching operation, the current flowing through the inductor repeats in triangular waveforms. The mean value ($I_{L1}(\text{mean})$) of the triangular wave current becomes $1/2$ of the peak value ($I_{L1}(\text{peak})$). (Fig. 3)

By controlling to make outline linking the peak of the inductor current to sine wave and removing switching ripple current, the smoothed current flowing from the AC input power source has sine wave shape.

FA5590 / FA5591 uses fixed on time control shown in Fig. 4. This control determines the on time of the output of IC (gate drive signal for Power Mos) with combination of the error amplifier output and saw tooth wave. While the load is constant, the output of the error amplifier is constant, and on time also stays constant. Since an inclination of inductor current depends on input voltage (an inclination of inductor current is proportional to input voltage) and on time is constant, the outline linking the peak of the inductor current becomes same AC waveform as the input voltage, which enables power-factor correction operation.

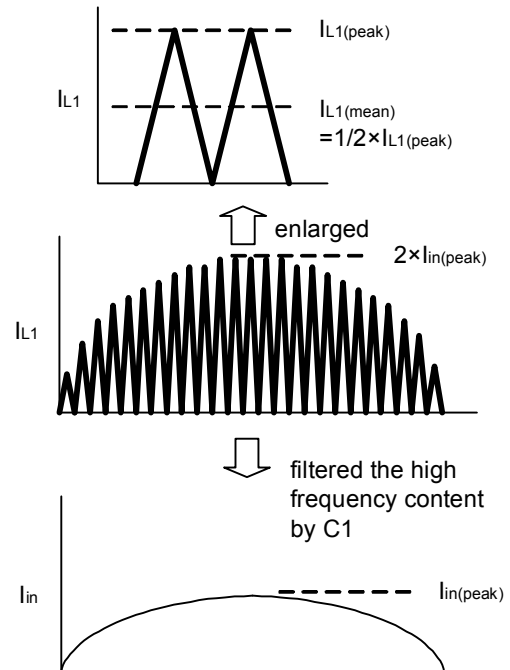


Fig.3 : Power-factor correction operation waveforms

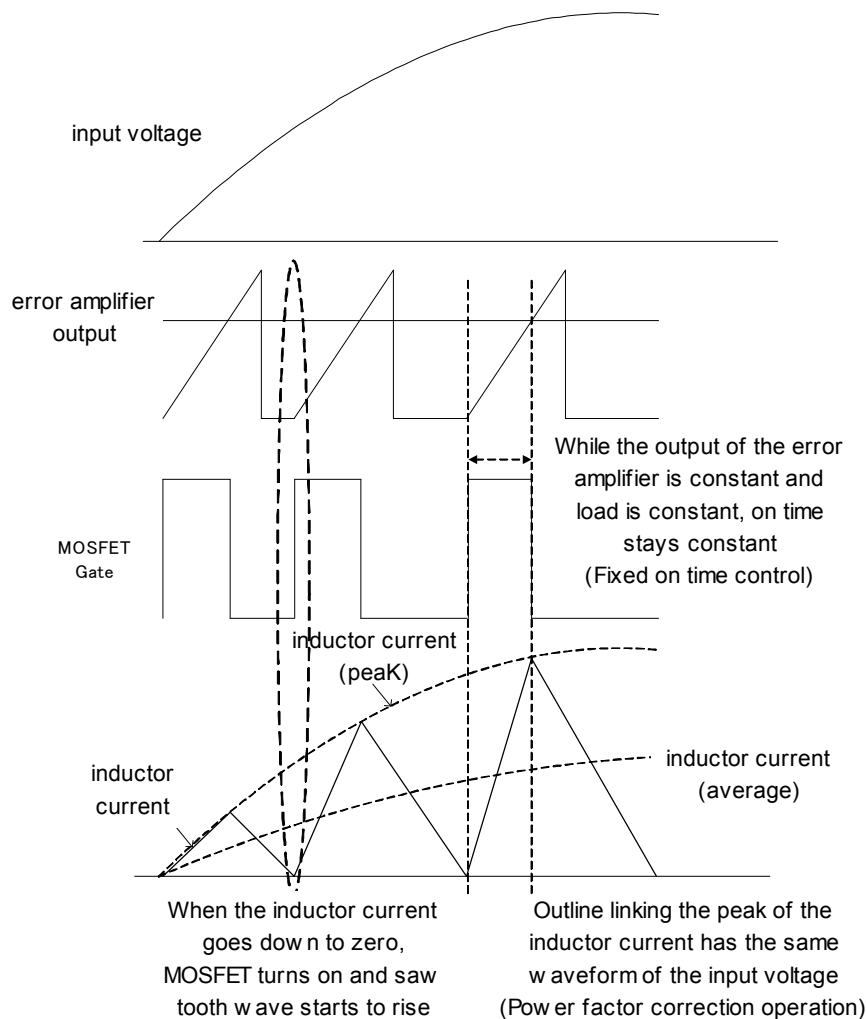


Fig.4 : Fixed on time control

10. Description of each circuit block

(1) Error amplifier circuit

The error amplifier is to make the output voltage constant with feedback control. For this IC, a transconductance type is used for the error amplifier.

The non-inverting input pin is connected to internal reference voltage of 2.5V (typ.).

The inverting input pin is fed with output voltage of the power-factor correction converter, and normally use divided voltage with resistors. To the inverting input, internal constant current source of 1.8 μ A is connected for FB open detection function.

The output of the error amplifier (COMP) is connected to the PWM comparator and controls the on time of the OUT output.

The output voltage of PFC contains much of ripple of frequency 2 times AC power line (50 or 60Hz). When this ripple component becomes largely appears in the output of the error amplifier, the power-factor correction converter does not stably operate. In order to obtain the stable operation, connect capacitors and a resistor between pin No.2 (COMP pin) and GND as shown in Fig.5.

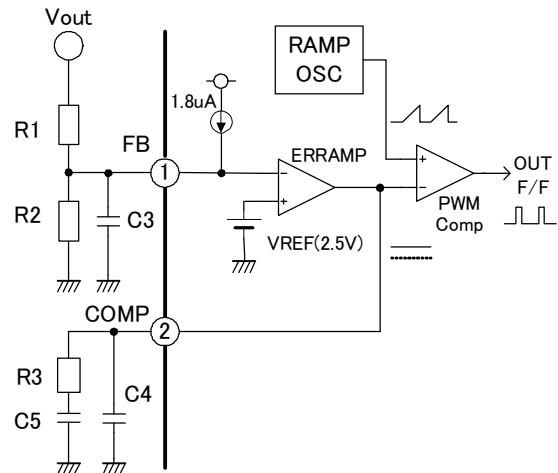


Fig.5 Error amplifier circuit

(2) Soft start circuit

FA5590/91 is equipped with soft start function to suppress rushing startup and overshoot of output voltage when starting.

The soft start circuit works after UVLO and standby is released and before the soft start cancellation voltage is exceeded. In the meantime, the soft start function restricts the startup speed of the output voltage by limiting the maximum on time to about 80% when the FB pin voltage is lower than the reference voltage. (Fig. 6) The on time limited by the soft start is cancelled when the FB pin voltage becomes higher than the soft start cancellation voltage.

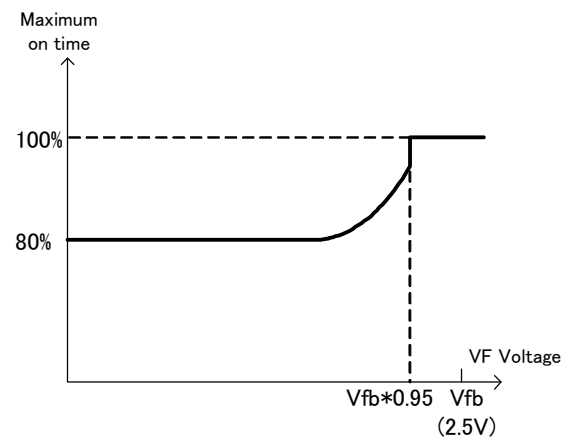


Fig.6 Maximum on time at soft start

(2) Overvoltage protection circuit (OVP)

This circuit is to limit the voltage when the output voltage of the power-factor correction converter exceeds the set value.

When this IC starts up or load changes sharply, the output voltage of the converter may exceed the set value. In such a case, this protect circuit works to control the output voltage.

FA5590/91 has dynamic OVP function to narrow the on time when the FB pin voltage becomes above 2.5V, and static OVP function to stop the output when it becomes higher than 1.09 times the reference voltage.

Normally the voltage of the FB pin is 2.5V, approximately same as the reference voltage of the error amplifier. When the output voltage rises due to starting up or sharp load changes and the voltage of the FB pin becomes higher than 2.5V, the on time narrows by the dynamic OVP function. When the voltage further rises and exceeds the comparator reference voltage, output voltage of the comparator(OVP) inverts to stop the OUT pulse.(Fig. 7)

When the output voltage turns below 1.05 times the reference voltage, the OUT pulse resumes.

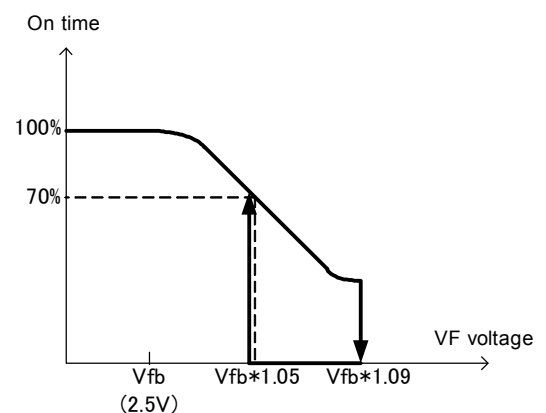


Fig.7 On time at overvoltage

(4) FB short-circuit/open detection circuit (standby circuit)

In the PFC circuit of booster type, if feedback voltage is not properly provided to the FB pin due to short-circuit or open-circuit around R1, R2, the error amplifier cannot control the constant voltage and the output voltage abnormally rises. In such a case, the overvoltage protection circuit also cannot operate because the detection of the output voltage is abnormal.

To avoid such situation, this IC is equipped with FB short-circuit detection circuit.

This circuit is composed of the reference voltage of 0.3V (typ.) and comparator (SP), and when the input voltage of the FB pin becomes 0.3V or lower due to such trouble as short-circuit of R2 or opening of R1, the output of the comparator (SP) inverts to stop the output of the IC and the IC stops operation resulting in standby state.

Once the voltage of the FB pin decreases to almost zero and the output of the IC stops, and then when the voltage of the FB pin returns to 0.3V or higher, the IC resumes from the standby state and the OUT pulse restarts.

When the connection between the FB pin and the node of voltage dividing resistors is broken, the FB pin voltage is forcefully raised by the internal constant current source of 1.8μA connected to the FB pin. Since the error amplifier output (COMP) voltage decreases as the FB pin voltage rises, the output voltage decreases or OUT output is stopped.

(5) Ramp oscillating circuit

The ramp oscillating circuit receives signal from the zero current detection circuit or restart circuit, and outputs the set signal of F/F for OUT output and saw tooth wave signal for deciding the duty of the PWM comparator.

(5-1) Maximum frequency limiting

The switching frequency of PFC in the critical mode has characteristic to rise at light load.

FA5590/91 has the maximum frequency limiting function to improve the efficiency at light load and limits the switching frequency to Fmax (Hz). (Fig. 9)

The maximum frequency Fmax depends on the resistance connected between the RT pin and GND.

When the switching frequency is lower than Fmax, the zero level of the inductor current is detected and MOSFET is turned on after the zero current detection delay Tzcd to adjust turning on take place at the bottom of Vds wave, as shown in Fig. 11.

In case of light load where the switching frequency is limited to Fmax, the zero level of the inductor current is detected and no turn-on occurs after the zero current detection delay, but turn-on occurs at the cycle of 1/Fmax, as shown in Fig. 12.

(6) Current detection circuit

The current detection circuit is composed of zero current detection and overcurrent detection. (Fig. 10)

(6-1) Zero current detection circuit

This IC performs the switching operation by self-oscillation in critical mode instead of the oscillator with the fixed frequency. The zero current detection circuit ZCD. Comp detects that the inductor current becomes zero to perform the critical mode operation.

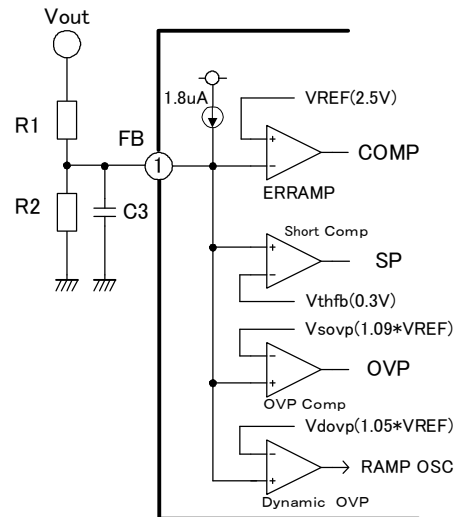


Fig.8 FB pin circuit

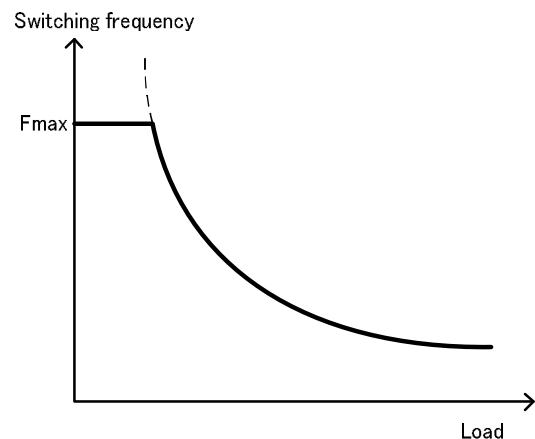


Fig.9 maximum frequency limiting

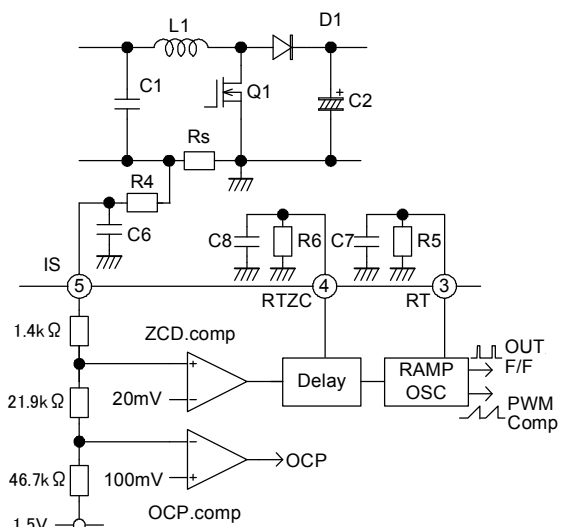


Fig.10 Current detection circuit

With the zero current detection, the voltage across the current detection resistor R_s connected to the GND line is fed to the IS pin, and it is compared by the zero current detection comparator, and when it becomes -4mV or more, the inductor current is regarded as zero level.

When the zero level is detected, the delay T_{zcd} is generated by the zero cross delay detection circuit, and then set the F/F for OUT to make MOSFET turn on.

(6-2) Overcurrent detection protective circuit

The overcurrent detection protective circuit detects the inductor current and protects MOSFET by turning off the OUT output when it becomes higher than a set current level. With the overcurrent detection, the voltage across the current detection resistance R_s connected to the GND is fed to the IS pin, and when the IS pin voltage compared by the overcurrent detection comparator becomes lower than -0.6V , it is regarded as overcurrent state.

When the overcurrent is detected, the F/F for OUT output is reset to make MOSFET turn off.

(7) Zero cross delay time setting circuit

V_{ds} between the drain and the sources of the MOSFET starts oscillating through resonance of L_1 and the parasitic capacitor component on the circuit just before the MOSFET turns on.

When the proper value of R_{tzc} , the turn on timing of MOSFET can be adjusted at the bottom of the voltage oscillation. This makes it possible to minimize the switching loss and the surge current generated at the turn-on. (Fig. 13)

When the R_{tzc} is smaller, the turn-on timing becomes earlier, and vice versa. (Fig. 14)

Since the optimum value of this R_{tzc} changes depending on the circuit and input/output conditions, tuning up is required so as to achieve an optimum state while evaluating the operation with actual circuit

(8) Restart timer

This IC utilizes self oscillation instead of the oscillator with fixed frequency, and in the steady operation, it turns on MOSFET with a signal from the zero current detector.

But in start up or light load condition, a trigger signal is required for starting up or stable operation.

This IC is provided with a restart timer, and when the output of IC continues turn off for $20\mu\text{s}$ or more, the trigger signal is automatically generated.

This signal can realize stable operation even when starting up or the load is light.

(9) Under voltage Lock out (UVLO)

UVLO is equipped to prevent circuit malfunction when supply voltage drops.

When the supply voltage rises from zero, the operation starts at 9.6V (typ.) for FA5590 and 13V (typ.) for FA5591. When the supply voltage decreases after the operation starts, either part number stops the operation at 9V (typ.). When UVLO is on and IC stops operation the OUT pin becomes LOW and cuts off the output. The current consumption of the IC decreases to $80\mu\text{A}$ or less.

(10) Output circuit

The output portion is of push-pull circuit and can directly drive the MOSFET. The peak current of the output portion is 1.0A maximum for sink and 1.0A maximum for source.

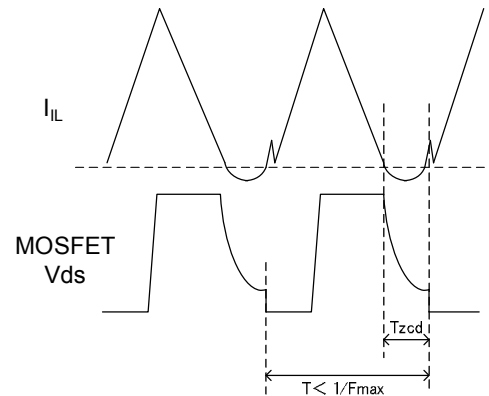


Fig.11 Waveforms when the switching frequency is lower than the maximum frequency F_{max}

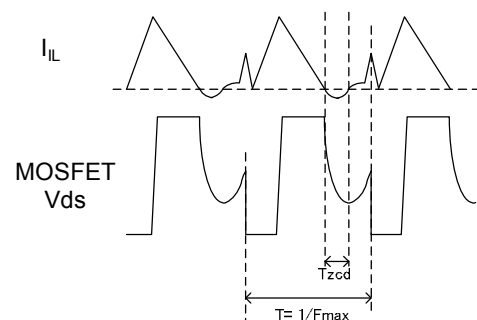


Fig.12 Waveforms when the switching frequency is limited to the maximum frequency F_{max}

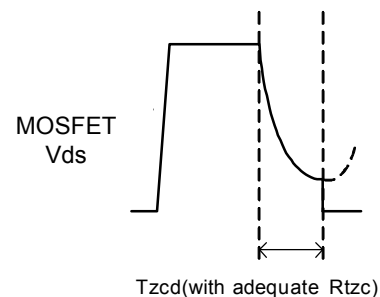


Fig.13 V_{ds} waveform at turn on (with adequate R_{tzc})

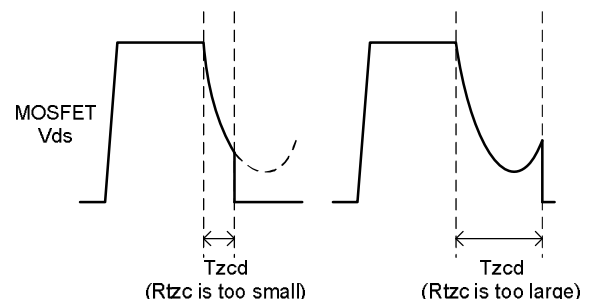


Fig.14 V_{ds} waveform at turn on (with inadequate R_{tzc})

11. How to use each pin and advice for designing

(1) Pin No.1 (FB pin)

Functions

- (i) Input of feedback signal of output voltage setting
- (ii) Detect short-circuit of FB pin
- (iii) Detect output overvoltage

How to use

- (i) Feedback signal input
 - Connection method
Connect the node between voltage dividing resistors for setting output voltage.
 - Operation
The output voltage V_{out} of PFC is controlled so that FB voltage matches the internal reference voltage (2.5V).
To detect FB pin open-circuit, pull-up current (I_{pullup}) is supplied to the FB pin. This current flows to GND via R2. For this reason, resistance R1, R2 should be set in consideration of this current when the output voltage (V_{out}) is set.

$$V_{out} = \left(\frac{V_{REF}}{R_2} - I_{pullup} \right) \times R_1 + V_{REF}$$

V_{REF} : Reference voltage = 2.5V(typ)

I_{pullup} : FB pin pull-up current = 1.8μA(typ)

To prevent malfunction due to noise, capacitor C3 of 100pF to 3300pF should be connected between the FB pin and GND.

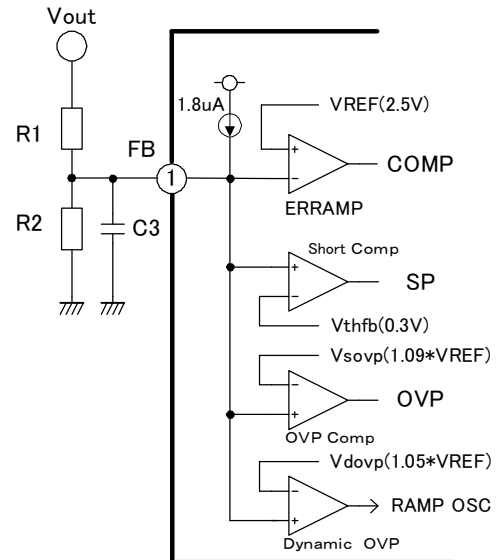


Fig.15 FB pin circuit

- (ii) FB pin short-circuit detection
 - Connection method
Same as for the (i) Feedback signal input
 - Operation
When the input voltage of the FB pin becomes 0.3V or lower due to short-circuit of R2, the output of the comparator (SP) inverts to stop the output of the IC.
- (iii) Output overvoltage detection
 - Connection method
Same as for the (i) Feedback signal input
 - Operation
Normally the voltage of the FB pin is 2.5V almost same as the reference voltage of the error amplifier. When the output voltage rises for some reason and the voltage of the FB pin reaches the comparator reference voltage (1.09*VREF), the output of the comparator (OVP) inverts to stop the OUT pulse. If the output voltage returns to the normal value, the OUT pulse resumes.

(2) Pin No.2 (COMP pin)

Functions

- (i) Phase compensation of internal ERRAMP output

How to use

- (i) Phase compensation of internal ERRAMP output
 - Connection method
Connect C, R between COMP pin and GND as shown in Fig. 16.
 - Operation
Connecting C, R to the COMP pin suppress ripple component at 2 times the frequency of the AC line that appears in the FB output.

(Reference)

Example of application circuit: $C_4=0.1\mu F$
 $C_5=0.15\mu F$
 $R_3=68k\Omega$

The above is a reference example, and it should be decided by sufficiently verifying with actual application circuit.

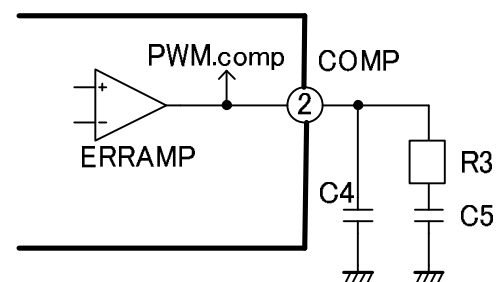


Fig.16 COMP pin circuit

(3) Pin No.3 (RT pin)
Functions

- (i) Set maximum on time
- (ii) Set maximum oscillation frequency

How to use

- (i) Set maximum on time
In the PFC circuit of booster type, on time T_{on} in each switching cycle with input and output conditions is theoretically expressed by the following formula.

$$T_{on} = \frac{2 \times L_p \times P_o}{V_{ac}^2 \times \eta}$$

Input Voltage (V_{rms}) : V_{ac}

Inductor (H) : L_p

Maximum Output Power (W) : P_o

Efficiency : η

The maximum on time T_{onmax} must be set equal to or more than the on time at minimum input voltage V_{ac} (min) at which the on time is maximum. In soft start, the maximum on time is limited to 80%, and therefore, the maximum on time should be set as shown by the following formula.

$$T_{onmax} > \frac{2 \times L_p \times P_o}{V_{ac(min)}^2 \times \eta \times 0.8}$$

- (ii) Set maximum oscillation frequency

To improve the efficiency at light load, FA5590N/91N limits switching frequency at light load to F_{max} (Hz). The maximum frequency F_{max} depends on the resistance connected between RT pin and GND.

- Connection method

Connect R5 between RT pin and GND as shown in Fig. 17. For the resistance dependency of the maximum on time and maximum oscillation frequency, see Chapter 8. Characteristic Curve.

The current sourced from the RT pin changes depending on the resistance connected. When R5 is relatively large, for example, 82k Ω , the current is about 10 μ A. When the current is relatively small, it is recommended to connect a capacitor of about 0.01 μ F in parallel to the resistor to stabilize the RT voltage, as shown in Fig. 17.

(4) pin No. 4 (RTZC pin)
Function

- (i) Set zero current detection delay time

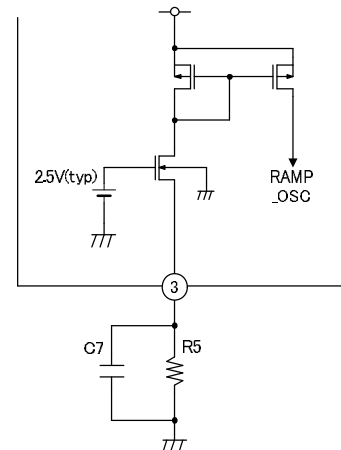
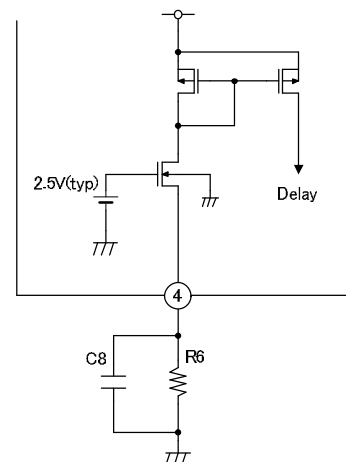
How to use

- (i) Set zero current detection delay time
Select a resistance value so as to set such delay time that MOSFET will turn on at the bottom of the v_{ds} waveform. (V_{ds} is almost 0V)

- Connection method

Connect R6 between RTZC pin and GND as shown in Fig. 18. For the resistance dependency of the delay time, see chapter 8. Characteristic Curve.

Like the RT pin as mentioned the previous section, the sourced current is small, and it is recommended to connect a capacitor of about 0.01 μ F in parallel to the resistor, as shown in the figure.


Fig.17 RT pin circuit

Fig.18 RTZC pin circuit

(5) Pin No.5 (IS pin)

Functions

- (i) Detect zero current through the inductor
- (ii) Detect overcurrent and turn off OUT output

How to use

The maximum threshold voltage V_{thcsh} of the IS pin is -0.58V(max).

The current detection resistance R_s is set so that necessary current can be supplied for this V_{thcsh} .

With maximum output P_o (W) and minimum input voltage V_{ac} (min), the maximum value of peak current (I_{LP} (max)) through the inductor can be approximately expressed by the following formula.

$$I_{LP(max)} = \frac{2 \times \sqrt{2} \times P_o}{\eta \times V_{ac(min)}}$$

Therefore, the value of R_s (Ω) is determined as follows.

$$R_s < \frac{-V_{thIS}}{I_{LP(max)}} = \frac{0.58}{I_{LP(max)}}$$

- Connection method

Connect the current detection resistor R_s between the source pin (GND) of MOSFET and the minus lead of the input capacitor (C_1). The voltage across R_s is fed to the IC as the current/voltage conversion signal.(Fig.19)

- Operation

- (i) Detect zero current through the inductor
The internal reference voltage and the internally divided voltage of the IS pin are inputted to the ZCD comparator, and when the IS pin voltage becomes larger than -10mV, the comparator output inverts and turns on the OUT output.
- (ii) Detect overcurrent and turn off OUT output
When the IS pin voltage becomes smaller than -0.6V, the comparator output signal inverts and turns off the OUT output.

【Additional explanation】

When MOSFET turns on, the gate driving current of MOSFET and surge current due to discharging the parasitic capacitors run to the current detection resistance R_s . Large surge current may cause malfunction following disturbed input current waveform. Depending on the amperage of the surge current or timing, whisker-like pulse may be mixed in the turn-on portion of the OUT pulse of the IC. Normally, therefore, a CR filter is connected as shown in Fig.19. The cutoff frequency of this CR filter must be set sufficiently higher than the switching frequency so that it will not affect the normal operation. It is recommended to set this cutoff frequency to about 1 to 2 MHz.

$$\frac{1}{2 \times \pi \times C_6 \times R_4} \approx 1 \text{ to } 2 \text{ [MHz]}$$

Since the threshold level is made through resistance dividing voltage as shown in Fig.19, the input resistor R_4 is recommended to be not higher than 100 Ω . The voltage rating of the IS pin is -5V.

In case of an ordinary boosting circuit, rush current to charge the output smoothing capacitor C_2 runs at the moment the ac input voltage is connected. This current may become far larger in comparison with the input current during normal operation. As a result, far larger voltage may also be applied to the IS pin than the ordinary case.

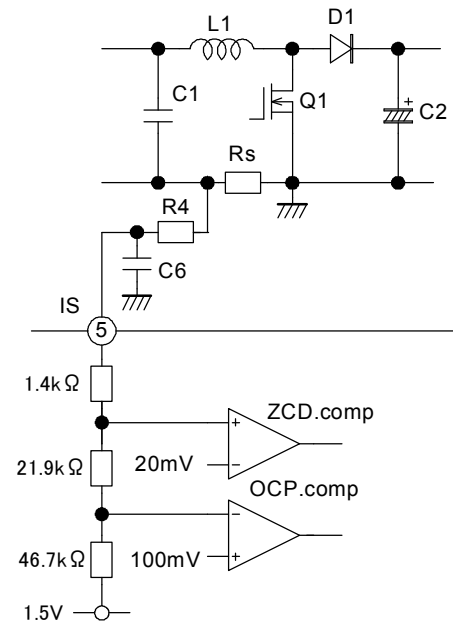


Fig.19 IS pin circuit

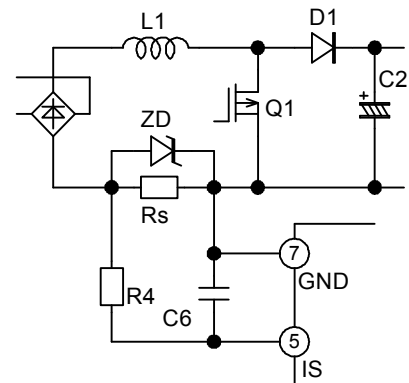


Fig.20 IS pin protection circuit (1)

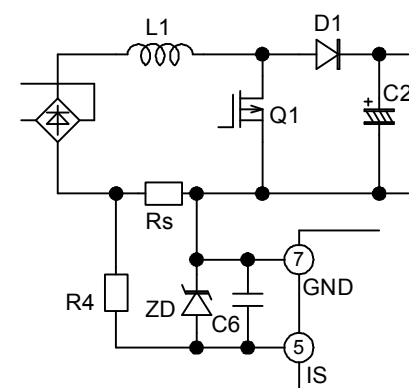


Fig.21 IS pin protection circuit (2)

In order to avoid damage, protective circuit must be taken in design so that voltage higher than $-10V (\leq 10ms)$, absolute maximum rating, will not be applied to the IS pin even when such AC input voltage is connected. If voltage higher than the rating is predicted to be applied to the IS pin, use rush preventive circuit suppress rushing current or place Zener diode shown in Fig. 20 and Fig. 21.

(6) Pin No.6 (GND pin)

Function

This voltage of GND pin is the reference for each portion of whole circuits.

(7) Pin No.7 (OUTpin)

Function

This drives MOSFET.

How to use

- Connection method
Connect it to the gate terminal of MOSFET through resistance.(Fig.22)
- Operation
During the period when turn on MOSFET, the output state is high, and the output voltage is almost VCC.
During the period when turn off MOSFET, the output state is low, and the output voltage is almost 0V.
- Additional explanation
The gate resistor is connected to limit the current of the OUT pin and prevent oscillation of the gate terminal voltage. The rating of the output current is 0.5A for source and 1A for sink.
Using the connections shown in Fig.23 and Fig.24, it is possible to independently set the gate driving current of turning on and off MOSFET.

(8) Pin No. 8 (VCC pin)

Function

- (i) Supply the power of IC.

How to use

- (i) Supply the power of IC.
- Connection method
Connect the start up resistor R7 between VCC pin and Voltage line after rectifying from AC line, which supplies power before IC starts switching operation.
In general application, the power is provided from the auxiliary winding of the transformer through D2 during operation.
In some application, DC power supply can be connected.
- Operation
In the application with out DC power supply to feed VCC pin, the current through start up resistor R7 charges the smoothing capacitors C5 and C9, and when VCC voltage rises to the on threshold voltage of UVLO, the IC starts operating. Before starting operation, it is necessary to supply current higher than 80uA (max), the startup current of the IC. During steady operation, the VCC is supplied from the auxiliary winding of the inductor. (Fig. 27)

When the supply voltage rises from zero, the operation starts at 9.6V (typ.) for FA5590 and 13V (typ.) for FA5591.

If the supply voltage decreases after the operation starts, the operation stops at 9V (typ.) by UVLO for both ICs. After IC stops operation due to UVLO, the OUT pin is Low state to cut off the output.

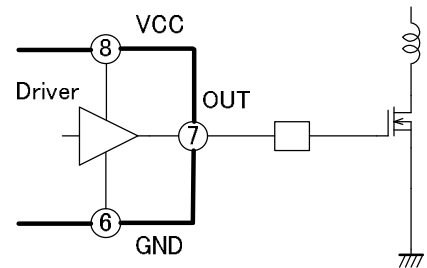


Fig.22 OUT pin circuit (1)

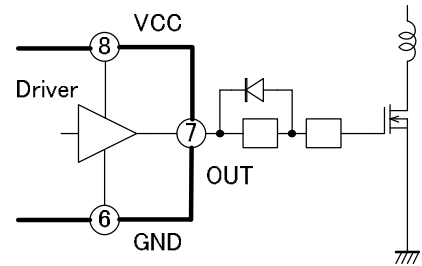


Fig.23 OUT pin circuit (2)

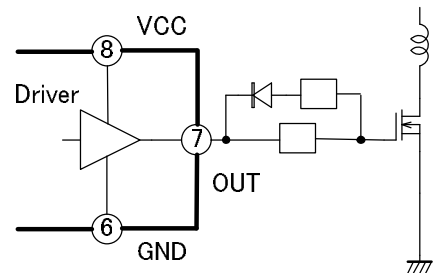


Fig.24 OUT pin circuit (3)

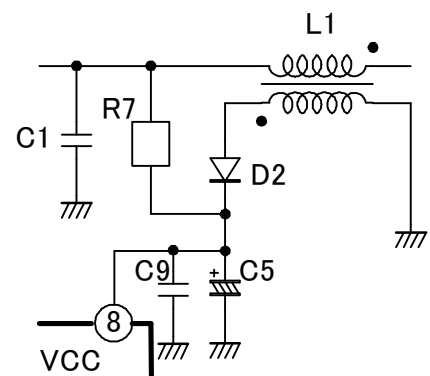


Fig.25 VCC pin circuit (1)

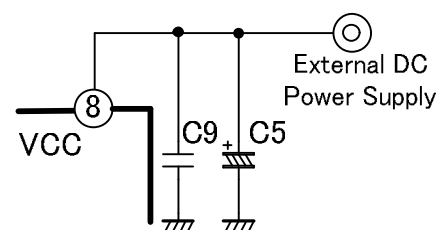


Fig.26 VCC pin circuit (2)

- Additional explanation

UVLO is preventive function to keep the circuit from malfunction when the supply voltage decreases.

With the start up resistor R7, it is necessary to supply current of 80μA or higher, the startup current, until start operating, and the following formula must be satisfied.

$$R7 < \frac{\sqrt{2} \times V_{ac(min)} - V_{on(max)}}{20 \times 10^{-6}}$$

V_{on(max)}: Low voltage ON threshold voltage of UVLO

FA5590 10.6V(max)

FA5591 14V(max)

The value of R7 expressed with the formula is, however, at least necessary and minimum condition to start the IC, and actually it should be decided considering the starting up time required for each application circuit.

This starting up time must be examined by measuring in actual circuit operation.

During the steady operation, V_{cc} is supplied from the auxiliary winding of the transformer. But there is some time delay until the auxiliary winding voltage sufficiently rises after the IC starts switching operation. To prevent V_{cc} from decreasing to the off threshold voltage of UVLO, it is necessary to decide the capacitance of the C5 connected to V_{cc}. Since this time delay differs depending on the circuit, it should be decided after checking with actual circuit

It is also recommended to place the ceramic capacitor C9 (about 0.1μF) to remove switching noise.

(9) Minus voltage of each pin

In some cases, the voltage oscillation of V_{ds} just before MOSFET turns on is applied to the OUT pin through parasitic capacitors, etc. and minus voltage may be added to the OUT pin. If this minus voltage is large, the parasitic element inside the IC is activated, and the IC may malfunction.

If this minus voltage is expected to exceed -0.3V, Schottky barrier diode should be connected between the OUT pin and GND. With the forward voltage of the Schottky barrier diode, the minus voltage can be clamped.

For other pins as well, care should be taken so that minus voltage will not be applied in the same way.

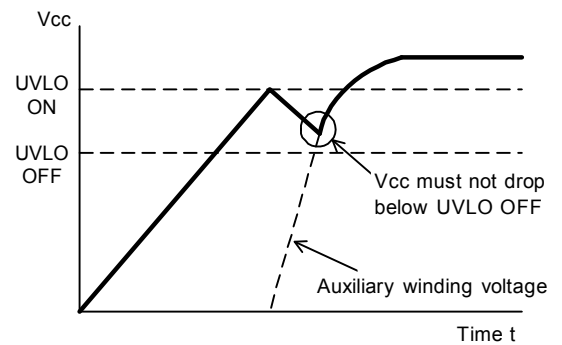


Fig.27 Vcc voltage at startup

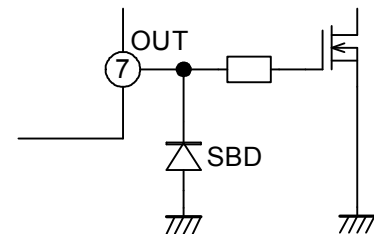


Fig.28 Protection circuit of OUT pin against the negative voltage

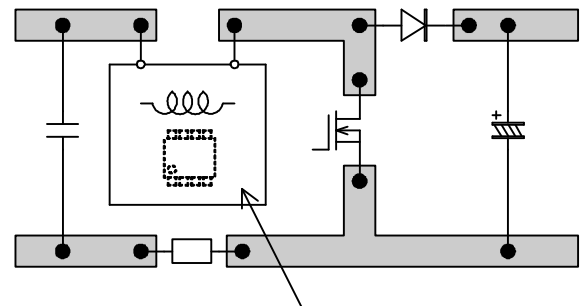
12. Advice for design

(1) Advice in pattern designing

Main circuit MOSFET, inductor, diodes, etc. perform switching under high voltage and large current. If wiring of IC or signals inputted to IC gets too near such main circuit parts, they may operate erratically upon being affected by noise generated there.

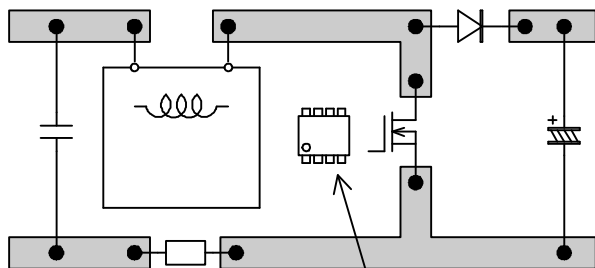
Attention must be paid particularly in following cases (examples of faulty cases).

- IC is arranged under inductor or other main circuit parts, or immediately behind main circuit parts on double sided circuit board (Fig. 29)
- IC is arranged close to inductor, MOSFET or diode (Fig. 30)
- Signal wiring is placed under inductor or near MOSFET or diode (Fig. 31)



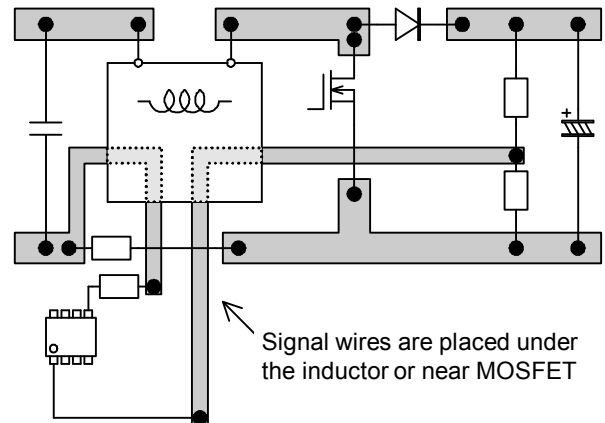
IC is placed under the inductor

Fig.29 Bad example (1)



IC is placed just beside the inductor, MOSFET

Fig.30 Bad example (2)



Signal wires are placed under the inductor or near MOSFET

Fig.31 Bad example (3)

(2) Example of GND wiring around IC

Notes)

Wiring is exemplified for you to understand how to connect the GND line.

Noise and incidental erratic operations differ from one instrument to another. Adopting any wiring exemplified in Fig. 32 will not necessarily guarantee normal operations of your instruments.

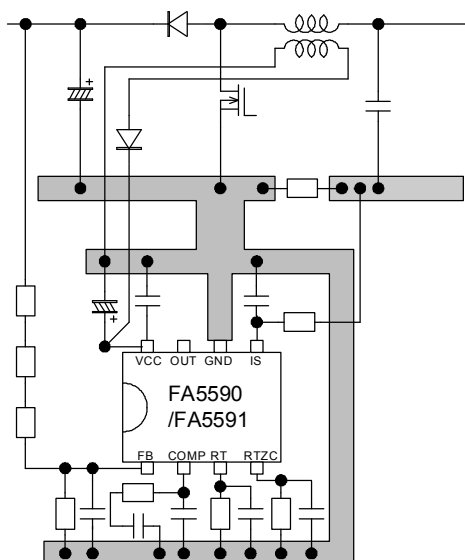


Fig.32 Good example of GND wiring around IC

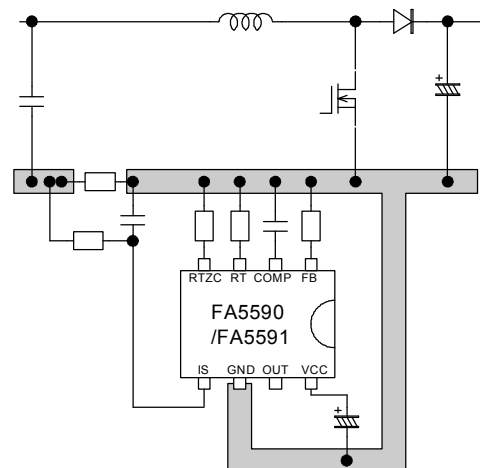
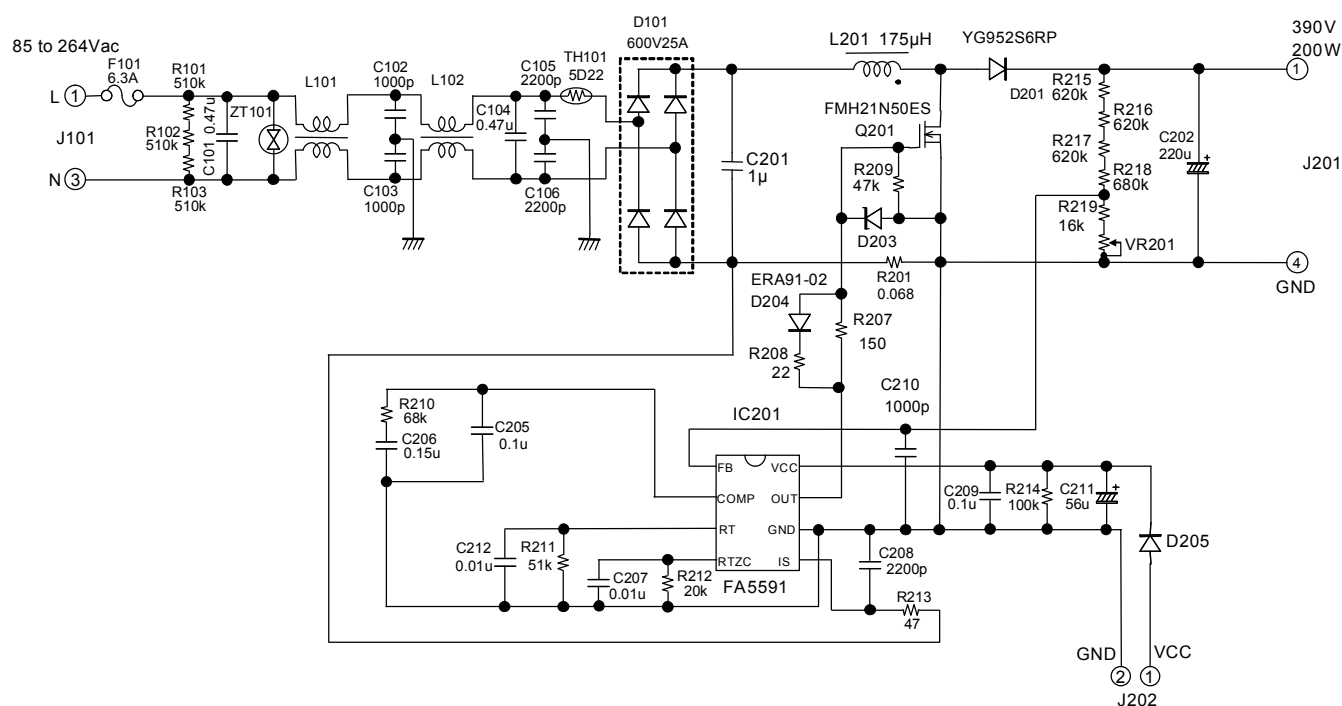


Fig.33 Bad example of GND wiring around IC
(GND is common to signal line parts and main circuit)

13. Example of application circuit (390V / 0.5A output)



Note) This application circuit is a reference material for describing typical usage of this IC, and does not guarantee the operation or characteristics of the IC.

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